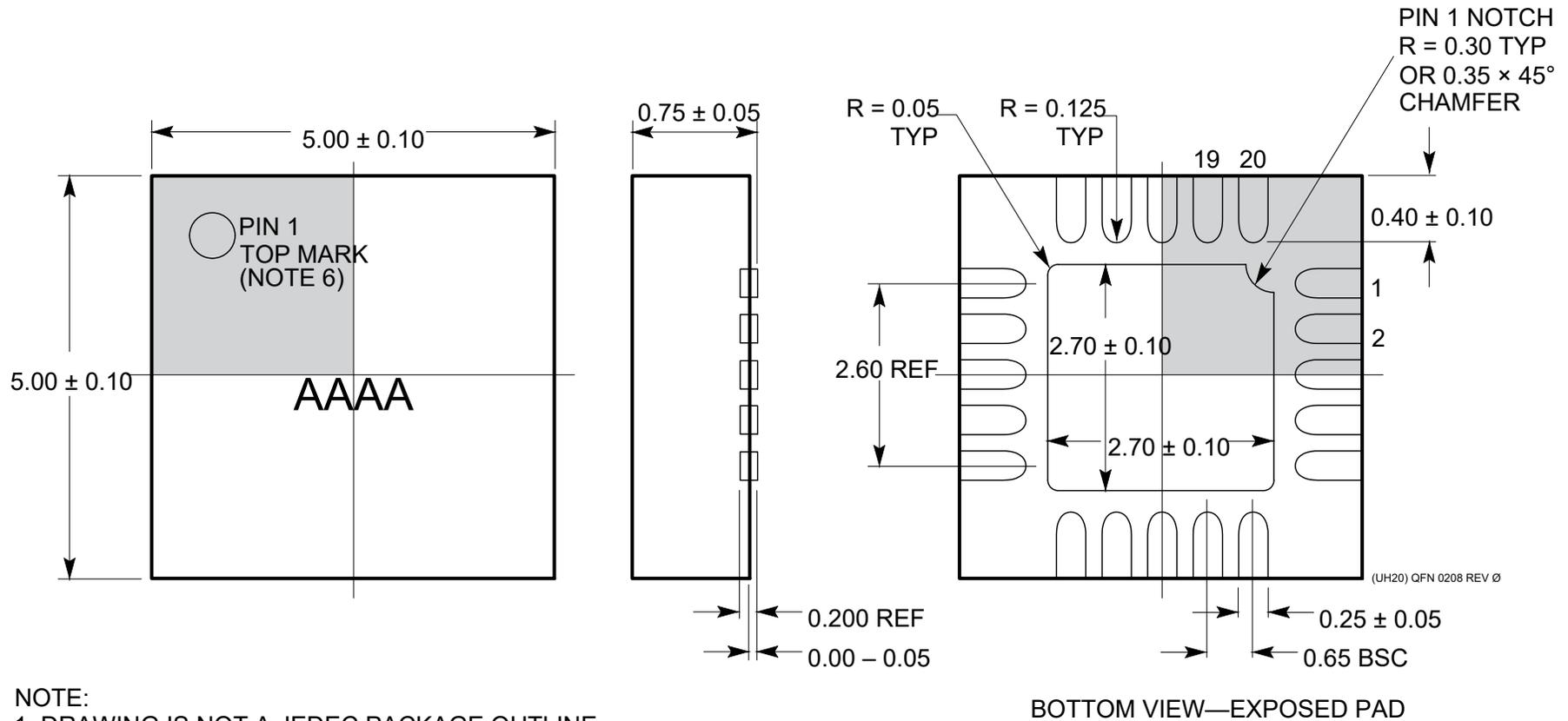


**DOCUMENT TYPE:** POD  
**DOCUMENT ID #:** 21-100696  
**REVISION:** C-000  
**DOCUMENT TITLE:** PACKAGE OUTLINE, 20L, THIN QFN, 5X5X0.75  
**EFFECTIVE DATE:** 02/09/2023  
**EXPIRATION DATE:**  
**CHANGE NUMBER:** 1180452  
**ORIGINATOR:** Bernard Go

**REASON FOR CHANGE:**

Updated with 2 pages for L-ADI/L-LTC and L-MXM marking orientation options.

OPTION A (FOR L-ADI/L-LTC PARTS)



NOTE:

1. DRAWING IS NOT A JEDEC PACKAGE OUTLINE
2. DRAWING NOT TO SCALE
3. ALL DIMENSIONS ARE IN MILLIMETERS
4. DIMENSIONS OF EXPOSED PAD ON BOTTOM OF PACKAGE DO NOT INCLUDE MOLD FLASH. MOLD FLASH, IF PRESENT, SHALL NOT EXCEED 0.20mm ON ANY SIDE
5. EXPOSED PAD SHALL BE SOLDER PLATED
6. SHADED AREA IS ONLY A REFERENCE FOR PIN 1 LOCATION ON THE TOP AND BOTTOM OF PACKAGE
7. REFERENCE LTC DWG # 05-08-1818
8. OPTION A AND B REFERS TO THE MARKING ORIENTATION VARIATION OF THE PARTS.
9. PACKAGE CODE: T2055+7



TITLE:  
PACKAGE OUTLINE, 20L, THIN QFN,  
5X5X0.75 mm

APPROVAL IRENE JEONG	DOCUMENT CONTROL NO. 21-100696	REV. C	1/1
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